Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .004” X .004”**

**Backside Potential: DRAIN**

**Mask Ref: IX9J**

**APPROVED BY: DK DIE SIZE .417” X .417” DATE: 7/21/21**

**MFG: MOTOROLA THICKNESS .008” P/N: IXFD64N50P**

**DG 10.1.2**

#### Rev B, 7/19/02